

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices –
Part 15: Discrete devices – Isolated power semiconductor devices**

**Dispositifs à semiconducteurs –
Partie 15: Dispositifs discrets – Dispositifs de puissance à semiconducteurs
isolés**





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SEMICONDUCTOR DEVICES –

Part 15: Discrete devices – Isolated power semiconductor devices

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IEC 60747-15 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

This third edition cancels and replaces the second edition published in 2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The intelligent power semiconductor modules (IPM), which was previously excluded from the first and second edition, is now included in this document (Annex C);
- b) The thermal resistance is described for each switch (6.2.4);
- c) Added isolation test between temperature sensor and terminals, in case there is an agreement with the user (6.1.2).

The text of this International Standard is based on the following documents:

Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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